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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

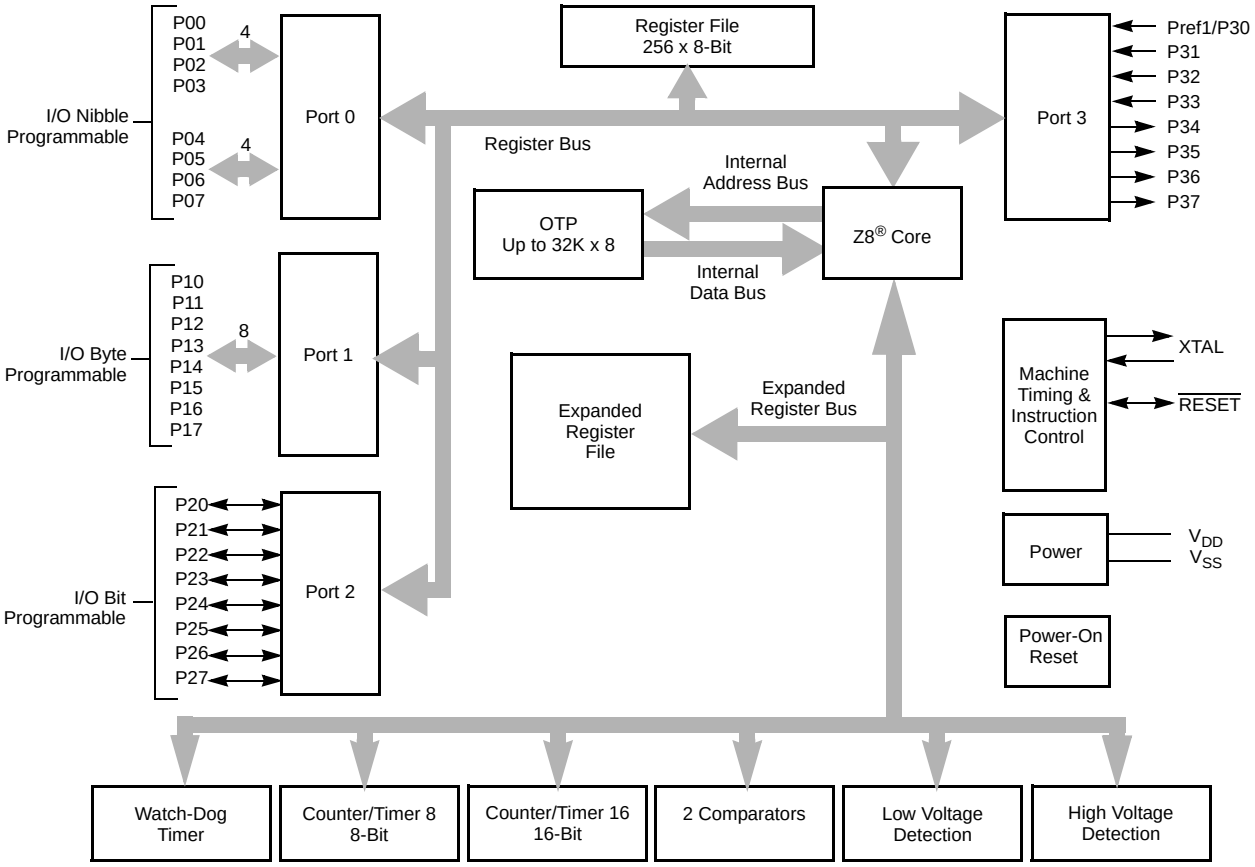
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	HLVD, POR, WDT
Number of I/O	24
Program Memory Size	16KB (16K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	237 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/zgp323hah2816c

List of Tables

Table 3. Power Connections

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}



Note: Refer to the specific package for available pins.

Figure 1. Functional Block Diagram

Absolute Maximum Ratings

Stresses greater than those listed in Table 8 might cause permanent damage to the device. This rating is a stress rating only. Functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period might affect device reliability.

Table 7. Absolute Maximum Ratings

Parameter	Minimum	Maximum	Units	Notes
Ambient temperature under bias	–40	125	° C	1
Storage temperature	–65	+150	° C	
Voltage on any pin with respect to V_{SS}	–0.3	7.0	V	2
Voltage on V_{DD} pin with respect to V_{SS}	–0.3	7.0	V	
Maximum current on input and/or inactive output pin	–5	+5	µA	
Maximum output current from active output pin	–25	+25	mA	
Maximum current into V_{DD} or out of V_{SS}		75	mA	

Notes:
1. See Ordering Information.
2. This voltage applies to all pins except the following: V_{DD}, P32, P33 and $\overline{\text{RESET}}$.

Standard Test Conditions

The characteristics listed in this product specification apply for standard test conditions as noted. All voltages are referenced to GND. Positive current flows into the referenced pin (see Figure 7).

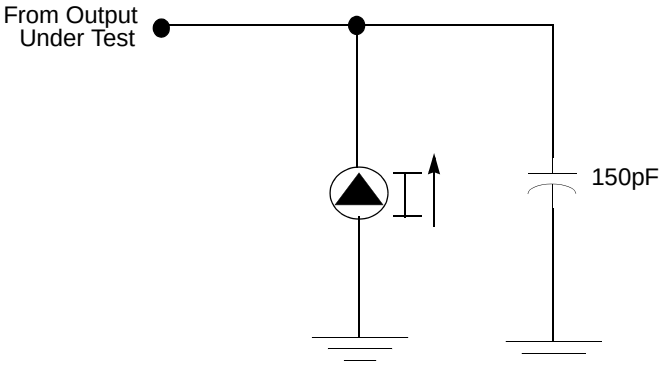


Figure 7. Test Load Diagram

Table 9. GP323HS DC Characteristics (Continued)

			T_A=0°C to +70°C					
Symbol	**Parameter**	**V_{CC}**	**Min**	**Typ(7)**	**Max**	**Units**	**Conditions**	**Notes**
I_{OL}	Output Leakage	2.0-5.5	–1		1	µA	V_{IN} = 0V, V_{CC}	
I_{CC}	Supply Current	2.0V		1	3	mA	at 8.0 MHz	1, 2
		3.6V		5	10	mA	at 8.0 MHz	1, 2
		5.5V		10	15	mA	at 8.0 MHz	1, 2
I_{CC1}	Standby Current (HALT Mode)	2.0V		0.5	1.6	mA	V_{IN} = 0V, Clock at 8.0MHz	1, 2, 6
		3.6V		0.8	2.0	mA	V_{IN} = 0V, Clock at 8.0MHz	1, 2, 6
		5.5V		1.3	3.2	mA	V_{IN} = 0V, Clock at 8.0MHz	1, 2, 6
I_{CC2}	Standby Current (Stop Mode)	2.0V		1.6	8	µA	V_{IN} = 0 V, V_{CC} WDT not Running	3
		3.6V		1.8	10	µA	V_{IN} = 0 V, V_{CC} WDT not Running	3
		5.5V		1.9	12	µA	V_{IN} = 0 V, V_{CC} WDT not Running	3
		2.0V		5	20	µA	V_{IN} = 0 V, V_{CC} WDT is Running	3
		3.6V		8	30	µA	V_{IN} = 0 V, V_{CC} WDT is Running	3
		5.5V		15	45	µA	V_{IN} = 0 V, V_{CC} WDT is Running	3
I_{LV}	Standby Current (Low Voltage)			1.2	6	µA	Measured at 1.3V	4
V_{BO}	V_{CC} Low Voltage Protection			1.9	2.0	V	8MHz maximum Ext. CLK Freq.	
V_{LVD}	V_{CC} Low Voltage Detection			2.4		V		
V_{HVD}	Vcc High Voltage Detection			2.7		V		

Notes:
1. All outputs unloaded, inputs at rail.
2. CL1 = CL2 = 100 pF.
3. Oscillator stopped.
4. Oscillator stops when V_{CC} falls below V_{BO} limit.
5. It is strongly recommended to add a filter capacitor (minimum 0.1 µF), physically close to VCC and V_{SS} pins if operating voltage fluctuations are anticipated, such as those resulting from driving an Infrared LED.
6. Comparator and Timers are on. Interrupt disabled.
7. Typical values shown are at 25 degrees C.

Table 10. GP323HE DC Characteristics

			T_A= -40°C to +105°C					
Symbol	**Parameter**	**V_{CC}**	**Min**	**Typ(7)**	**Max**	**Units**	**Conditions**	**Notes**
V_{CC}	Supply Voltage		2.0		5.5	V	See Note 5	5
V_{CH}	Clock Input High Voltage	2.0-5.5	0.8 V_{CC}		V_{CC}+0.3	V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	2.0-5.5	V_{SS}–0.3		0.4	V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	2.0-5.5	0.7 V_{CC}		V_{CC}+0.3	V		
V_{IL}	Input Low Voltage	2.0-5.5	V_{SS}–0.3		0.2 V_{CC}	V		
V_{OH1}	Output High Voltage	2.0-5.5	V_{CC}–0.4			V	I_{OH} = –0.5mA	

Table 11. GP323HA DC Characteristics

			T_A= -40°C to +125°C					
Symbol	**Parameter**	**V_{CC}**	**Min**	**Typ(7)**	**Max**	**Units**	**Conditions**	**Notes**
V_{CC}	Supply Voltage		2.0		5.5	V	See Note 5	5
V_{CH}	Clock Input High Voltage	2.0-5.5	0.8 V_{CC}		V_{CC}+0.3	V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	2.0-5.5	V_{SS}–0.3		0.4	V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	2.0-5.5	0.7 V_{CC}		V_{CC}+0.3	V		
V_{IL}	Input Low Voltage	2.0-5.5	V_{SS}–0.3		0.2 V_{CC}	V		
V_{OH1}	Output High Voltage	2.0-5.5	V_{CC}–0.4			V	I_{OH} = –0.5mA	
V_{OH2}	Output High Voltage (P36, P37, P00, P01)	2.0-5.5	V_{CC}–0.8			V	I_{OH} = –7mA	
V_{OL1}	Output Low Voltage	2.0-5.5			0.4	V	I_{OL} = 4.0mA	
V_{OL2}	Output Low Voltage (P00, P01, P36, P37)	2.0-5.5			0.8	V	I_{OL} = 10mA	
V_{OFFSET}	Comparator Input Offset Voltage	2.0-5.5			25	mV		
V_{REF}	Comparator Reference Voltage	2.0-5.5	0		V_{DD} -1.75	V		
I_{IL}	Input Leakage	2.0-5.5	–1		1	µA	V_{IN} = 0V, V_{CC} Pull-ups disabled	
R_{PU}	Pull-up Resistance	2.0V	200		700	KΩ	V_{IN} = 0V; Pullups selected by mask option	
		3.6V	50		300	KΩ		
		5.0V	25		175	KΩ		
I_{OL}	Output Leakage	2.0-5.5	–1		1	µA	V_{IN} = 0V, V_{CC}	
I_{CC}	Supply Current	2.0V		1	3	mA	at 8.0 MHz	1, 2
		3.6V		5	10	mA	at 8.0 MHz	1, 2
		5.5V		10	15	mA	at 8.0 MHz	1, 2
I_{CC1}	Standby Current (HALT Mode)	2.0V		0.5	1.6	mA	V_{IN} = 0V, Clock at 8.0MHz	1, 2, 6
		3.6V		0.8	2.0	mA	V_{IN} = 0V, Clock at 8.0MHz	1, 2, 6
		5.5V		1.3	3.2	mA	V_{IN} = 0V, Clock at 8.0MHz	1, 2, 6
I_{CC2}	Standby Current (Stop Mode)	2.0V		1.6	15	µA	V_{IN} = 0 V, V_{CC} WDT not Running	3
		3.6V		1.8	20	µA	V_{IN} = 0 V, V_{CC} WDT not Running	3
		5.5V		1.9	25	µA	V_{IN} = 0 V, V_{CC} WDT not Running	3
		2.0V		5	30	µA	V_{IN} = 0 V, V_{CC} WDT is Running	3
		3.6V		8	40	µA	V_{IN} = 0 V, V_{CC} WDT is Running	3
		5.5V		15	60	µA	V_{IN} = 0 V, V_{CC} WDT is Running	3
I_{LV}	Standby Current (Low Voltage)			1.2	6	µA	Measured at 1.3V	4
V_{BO}	V_{CC} Low Voltage Protection			1.9	2.15	V	8MHz maximum Ext. CLK Freq.	
V_{LVD}	V_{CC} Low Voltage Detection			2.4		V		

AC Characteristics

Figure 8 and Table 13 describe the Alternating Current (AC) characteristics.

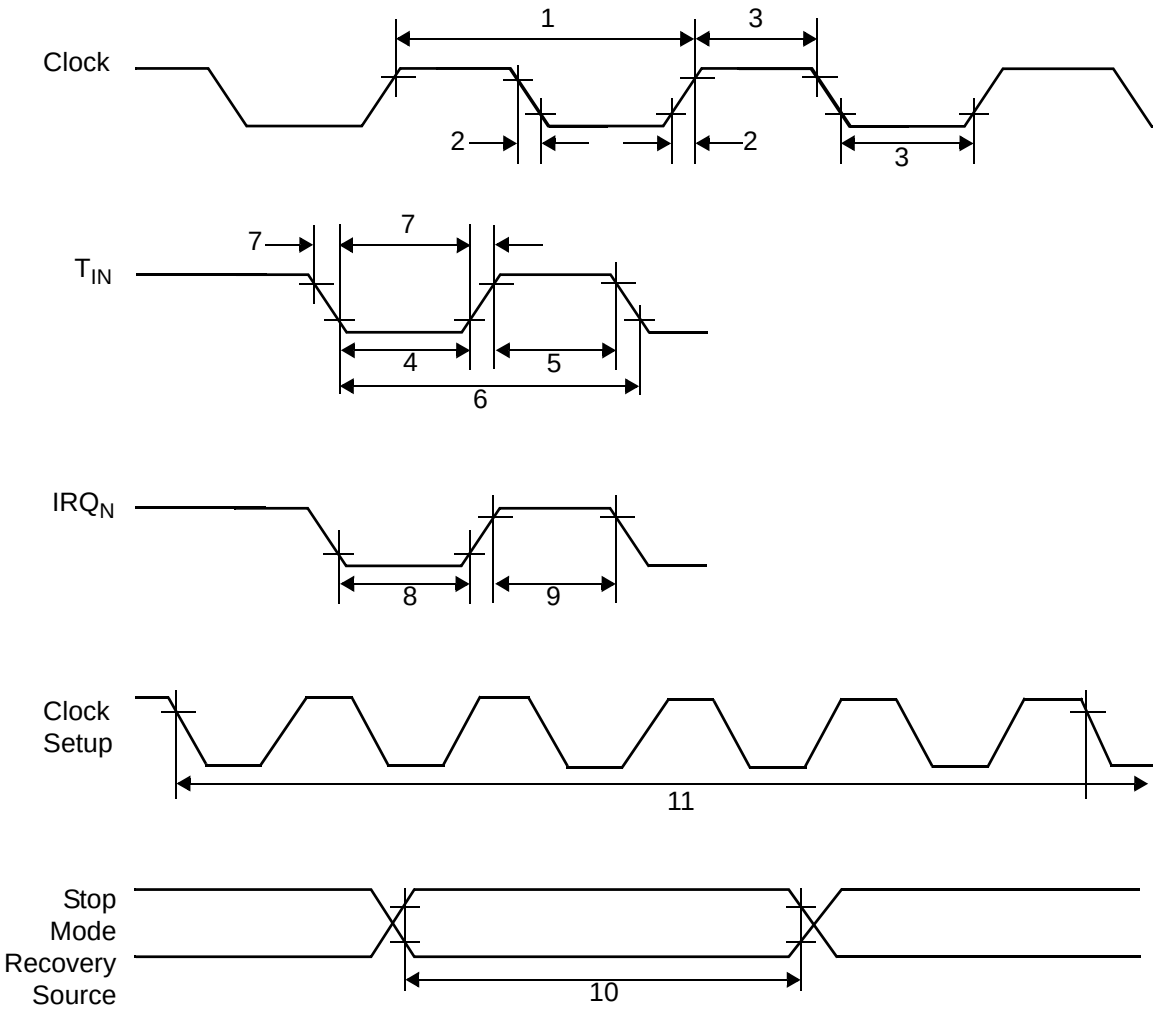


Figure 8. AC Timing Diagram

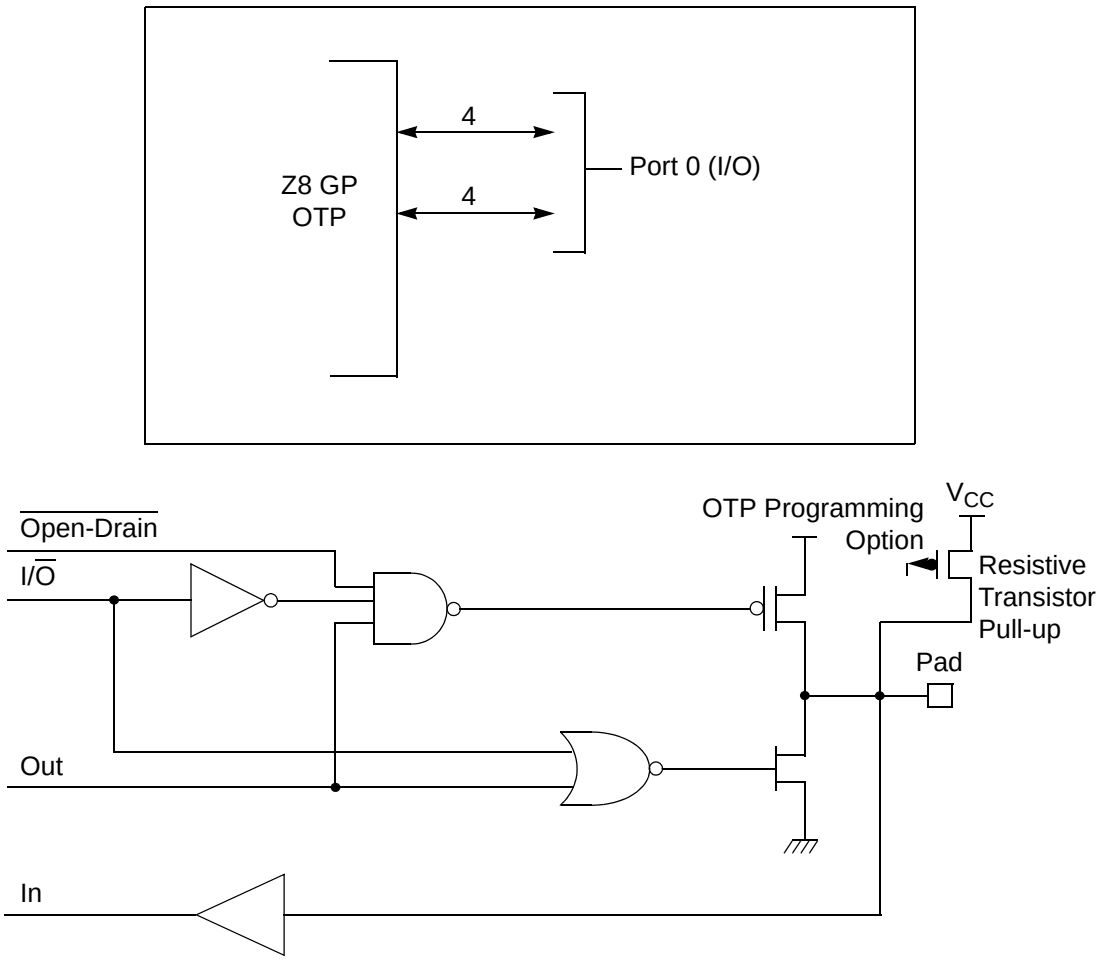


Figure 9. Port 0 Configuration

Port 1 (P17–P10)

Port 1 (see Figure 10) Port 1 can be configured for standard port input or output mode. After POR, Port 1 is configured as an input port. The output drivers are either push-pull or open-drain and are controlled by bit D1 in the PCON register.

Note: The Port 1 direction is reset to its default state following an SMR.

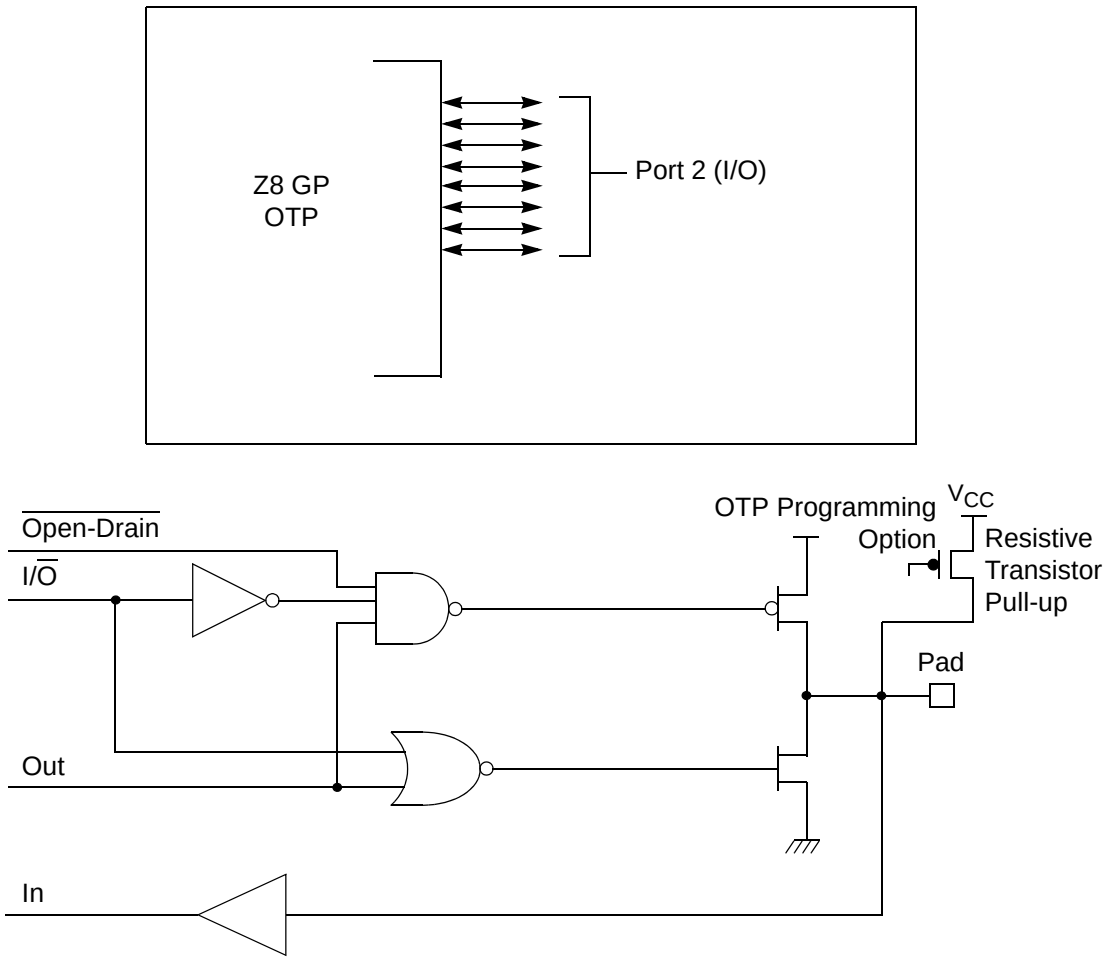


Figure 11. Port 2 Configuration

Port 3 (P37–P30)

Port 3 is a 8-bit, CMOS-compatible fixed I/O port (see Figure 12). Port 3 consists of four fixed input (P33–P30) and four fixed output (P37–P34), which can be configured under software control for interrupt and as output from the counter/timers. P30, P31, P32, and P33 are standard CMOS inputs; P34, P35, P36, and P37 are push-pull outputs.

The upper nibble of the register pointer (see Figure 16) selects which working register group, of 16 bytes in the register file, is accessed out of the possible 256. The lower nibble selects the expanded register file bank and, in the case of the Z8 GP family, banks 0, F, and D are implemented. A 0H in the lower nibble allows the normal register file (bank 0) to be addressed. Any other value from 1H to FH exchanges the lower 16 registers to an expanded register bank.

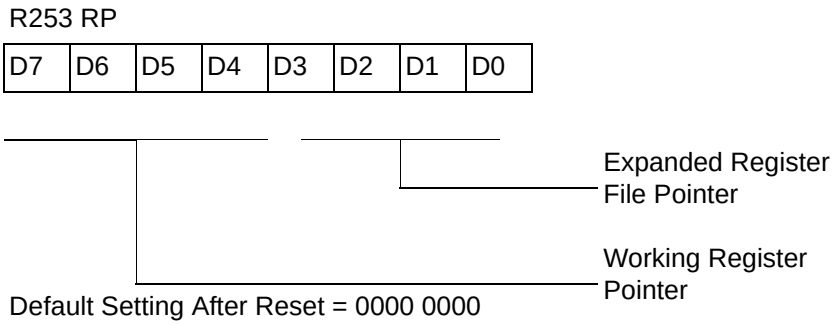


Figure 16. Register Pointer

Example: Z8 GP: (See Figure 15 on page 28)

R253 RP = 00h
R0 = Port 0
R1 = Port 1
R2 = Port 2
R3 = Port 3

But if:

R253 RP = 0Dh
R0 = CTR0
R1 = CTR1
R2 = CTR2
R3 = Reserved

Table 19. Interrupt Types, Sources, and Vectors

Name	Source	Vector Location	Comments
IRQ0	P32	0,1	External (P32), Rising, Falling Edge Triggered
IRQ1	P33	2,3	External (P33), Falling Edge Triggered
IRQ2	P31, T_{IN}	4,5	External (P31), Rising, Falling Edge Triggered
IRQ3	T16	6,7	Internal
IRQ4	T8	8,9	Internal
IRQ5	LVD	10,11	Internal

When more than one interrupt is pending, priorities are resolved by a programmable priority encoder controlled by the Interrupt Priority Register. An interrupt machine cycle activates when an interrupt request is granted. As a result, all subsequent interrupts are disabled, and the Program Counter and Status Flags are saved. The cycle then branches to the program memory vector location reserved for that interrupt. All ZGP323H interrupts are vectored through locations in the program memory. This memory location and the next byte contain the 16-bit address of the interrupt service routine for that particular interrupt request. To accommodate polled interrupt systems, interrupt inputs are masked, and the Interrupt Request register is polled to determine which of the interrupt requests require service.

An interrupt resulting from AN1 is mapped into IRQ2, and an interrupt from AN2 is mapped into IRQ0. Interrupts IRQ2 and IRQ0 can be rising, falling, or both edge triggered. These interrupts are programmable by the user. The software can poll to identify the state of the pin.

Programming bits for the Interrupt Edge Select are located in the IRQ Register (R250), bits D7 and D6. The configuration is indicated in Table 20.

Table 20. IRQ Register

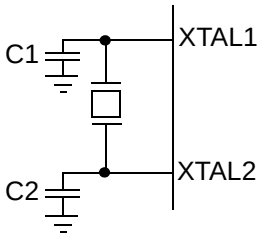
IRQ		Interrupt Edge	
D7	**D6**	**IRQ2 (P31)**	**IRQ0 (P32)**
0	0	F	F
0	1	F	R
1	0	R	F
1	1	R/F	R/F

Note: F = Falling Edge; R = Rising Edge

Clock

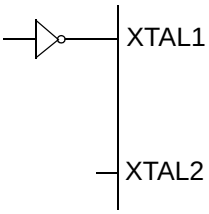
The device's on-chip oscillator has a high-gain, parallel-resonant amplifier, for connection to a crystal or ceramic resonator, or any suitable external clock source (XTAL1 = Input, XTAL2 = Output). The crystal must be AT cut, 1 MHz to 8 MHz maximum, with a series resistance (RS) less than or equal to 100 Ω. The on-chip oscillator can be driven with a suitable external clock source.

The crystal must be connected across XTAL1 and XTAL2 using the recommended capacitors (capacitance greater than or equal to 22 pF) from each pin to ground.

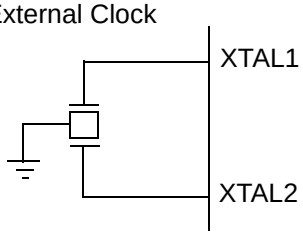


Crystal
C1, C2 = 33pF TYP *
f = 8MHz

* Preliminary value including pin parasitics



External Clock



Ceramic Resonator
f = 8mHz

Figure 31. Oscillator Configuration

Port 0 Output Mode (D2)

Bit 2 controls the output mode of port 0. A 1 in this location sets the output to push-pull, and a 0 sets the output to open-drain.

Stop-Mode Recovery Register (SMR)

This register selects the clock divide value and determines the mode of Stop Mode Recovery (Figure 33). All bits are write only except bit 7, which is read only. Bit 7 is a flag bit that is hardware set on the condition of Stop recovery and reset by a power-on cycle. Bit 6 controls whether a low level or a high level at the XOR-gate input (Figure 35 on page 59) is required from the recovery source. Bit 5 controls the reset delay after recovery. Bits D2, D3, and D4 of the SMR register specify the source of the Stop Mode Recovery signal. Bits D0 determines if SCLK/TCLK are divided by 16 or not. The SMR is located in Bank F of the Expanded Register Group at address 0BH.

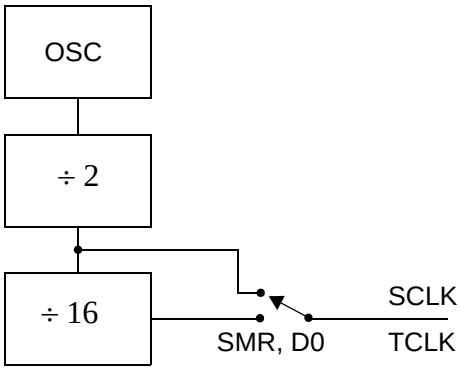


Figure 34. SCLK Circuit

Stop-Mode Recovery Source (D2, D3, and D4)

These three bits of the SMR specify the wake-up source of the Stop recovery (Figure 35 and Table 22).

Stop-Mode Recovery Register 2—SMR2(F)0DH

Table 21 lists and briefly describes the fields for this register.

Table 21. SMR2(F)0DH:Stop Mode Recovery Register 2*

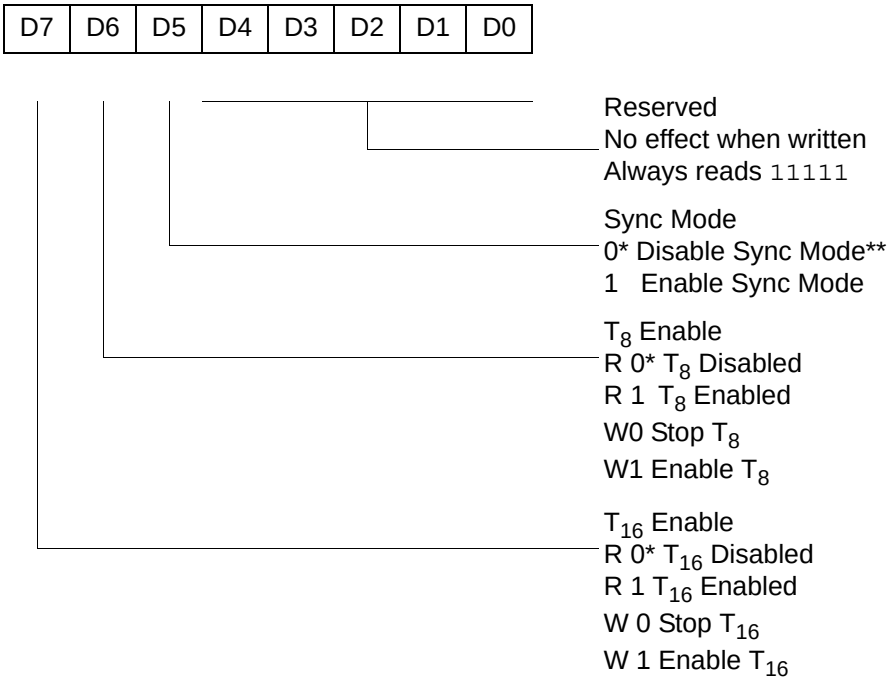
Field	Bit Position		Value	Description
Reserved	7-------		0	Reserved (Must be 0)
Recovery Level	-6------	W	0† 1	Low High
Reserved	--5-----		0	Reserved (Must be 0)
Source	---432--	W	000† 001 010 011 100 101 110 111	A. POR Only B. NAND of P23–P20 C. NAND of P27–P20 D. NOR of P33–P31 E. NAND of P33–P31 F. NOR of P33–P31, P00, P07 G. NAND of P33–P31, P00, P07 H. NAND of P33–P31, P22–P20
Reserved	------10		00	Reserved (Must be 0)

Notes:
* Port pins configured as outputs are ignored as a SMR recovery source.
† Indicates the value upon Power-On Reset

Notes: Take care in differentiating the Transmit Mode from Demodulation Mode. Depending on which of these two modes is operating, the CTR1 bit has different functions.

Changing from one mode to another cannot be performed without disabling the counter/timers.

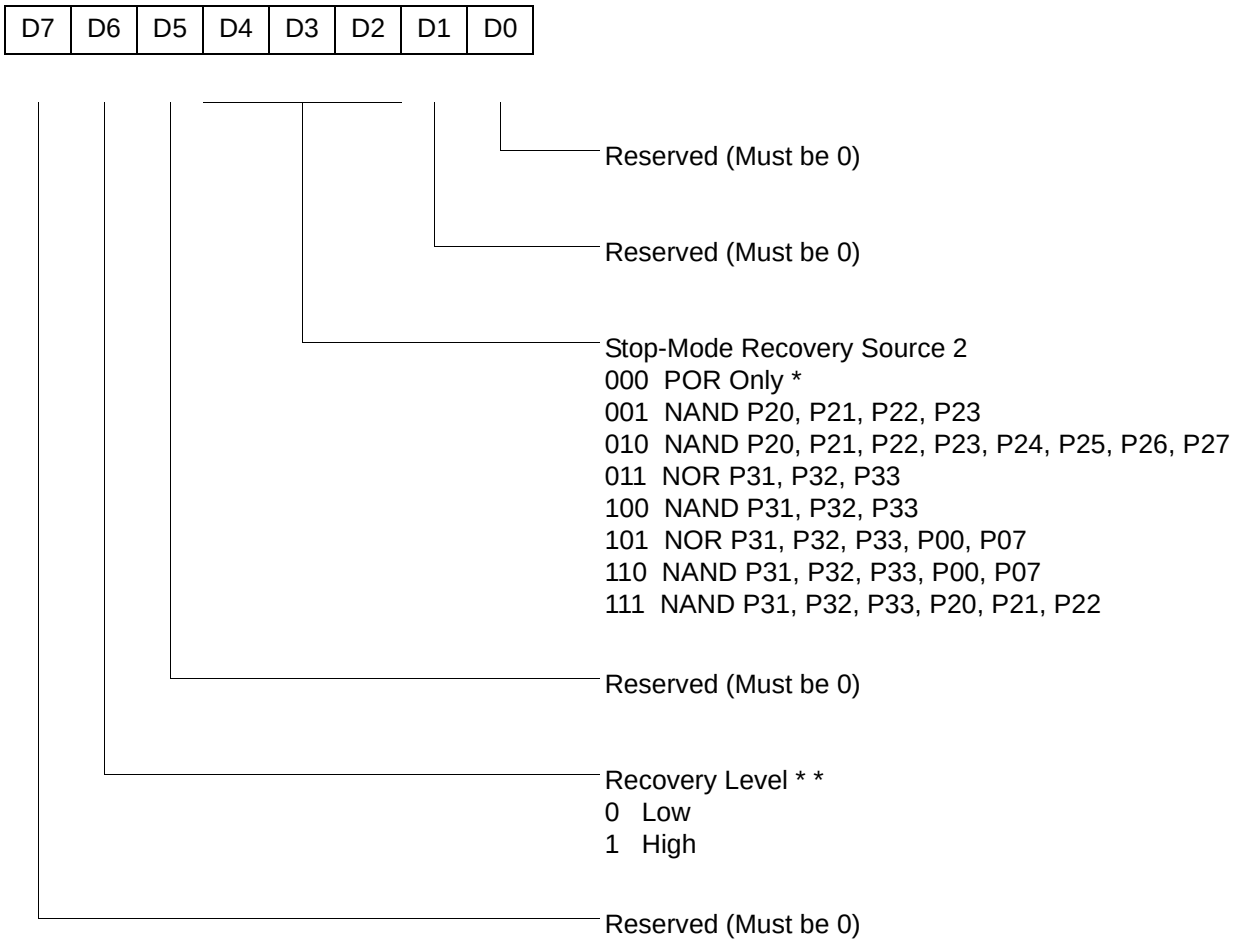
CTR3(0D)03H



* Default setting after reset.
** Default setting after reset. Not reset with a Stop Mode recovery.

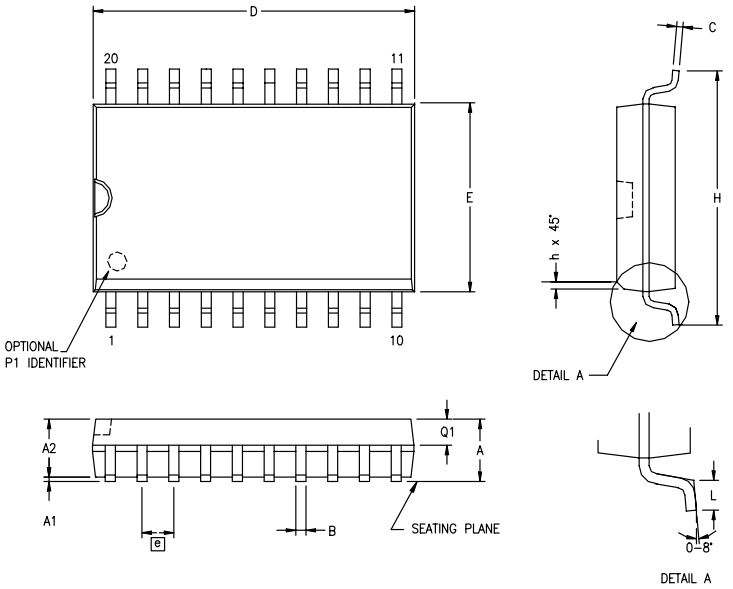
Figure 42. T8/T16 Control Register (0D)03H: Read/Write (Except Where Noted)

SMR2(0F)0DH



Note: If used in conjunction with SMR, either of the two specified events causes a Stop-Mode Recovery.
* Default setting after reset. Not reset with a Stop Mode recovery.
* * At the XOR gate input

Figure 46. Stop Mode Recovery Register 2 ((0F)0DH:D2–D4, D6 Write Only)



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.65	.094	.104
A1	0.10	0.30	.004	.012
A2	2.24	2.44	.088	.096
B	0.36	0.46	.014	.018
C	0.23	0.30	.009	.012
D	12.60	12.95	**.496**	.510
E	7.40	7.60	.291	.299
e	1.27 BSC		.050 BSC	
H	10.00	10.65	.394	.419
h	0.30	0.40	.012	.016
L	0.60	1.00	.024	.039
Q1	0.97	1.07	.038	.042

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

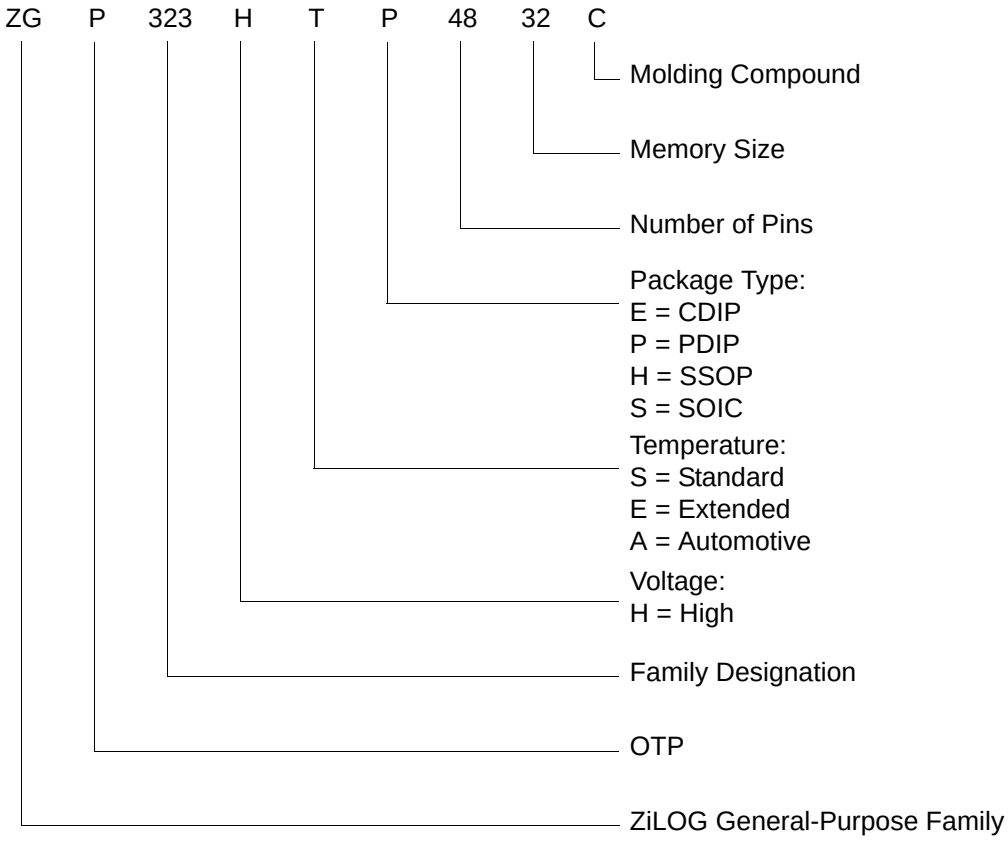
Figure 60. 20-Pin SOIC Package Diagram

8KB Standard Temperature: 0° to +70°C			
Part Number	**Description**	**Part Number**	**Description**
ZGP323HSH4808C	48-pin SSOP 8K OTP	ZGP323HSS2808C	28-pin SOIC 8K OTP
ZGP323HSP4008C	40-pin PDIP 8K OTP	ZGP323HSH2008C	20-pin SSOP 8K OTP
ZGP323HSH2808C	28-pin SSOP 8K OTP	ZGP323HSP2008C	20-pin PDIP 8K OTP
ZGP323HSP2808C	28-pin PDIP 8K OTP	ZGP323HSS2008C	20-pin SOIC 8K OTP

8KB Extended Temperature: -40° to +105°C			
Part Number	**Description**	**Part Number**	**Description**
ZGP323HEH4808C	48-pin SSOP 8K OTP	ZGP323HES2808C	28-pin SOIC 8K OTP
ZGP323HEP4008C	40-pin PDIP 8K OTP	ZGP323HEH2008C	20-pin SSOP 8K OTP
ZGP323HEH2808C	28-pin SSOP 8K OTP	ZGP323HEP2008C	20-pin PDIP 8K OTP
ZGP323HEP2808C	28-pin PDIP 8K OTP	ZGP323HES2008C	20-pin SOIC 8K OTP

8KB Automotive Temperature: -40° to +125°C			
Part Number	**Description**	**Part Number**	**Description**
ZGP323HAH4808C	48-pin SSOP 8K OTP	ZGP323HAS2808C	28-pin SOIC 8K OTP
ZGP323HAP4008C	40-pin PDIP 8K OTP	ZGP323HAH2008C	20-pin SSOP 8K OTP
ZGP323HAH2808C	28-pin SSOP 8K OTP	ZGP323HAP2008C	20-pin PDIP 8K OTP
ZGP323HAP2808C	28-pin PDIP 8K OTP	ZGP323HAS2008C	20-pin SOIC 8K OTP
Replace C with G for Lead-Free Packaging			

Example


ZG P 323 H T P 48 32 C
Molding Compound
Memory Size
Number of Pins
Package Type:
E = CDIP
P = PDIP
H = SSOP
S = SOIC
Temperature:
S = Standard
E = Extended
A = Automotive
Voltage:
H = High
Family Designation
OTP
ZiLOG General-Purpose Family